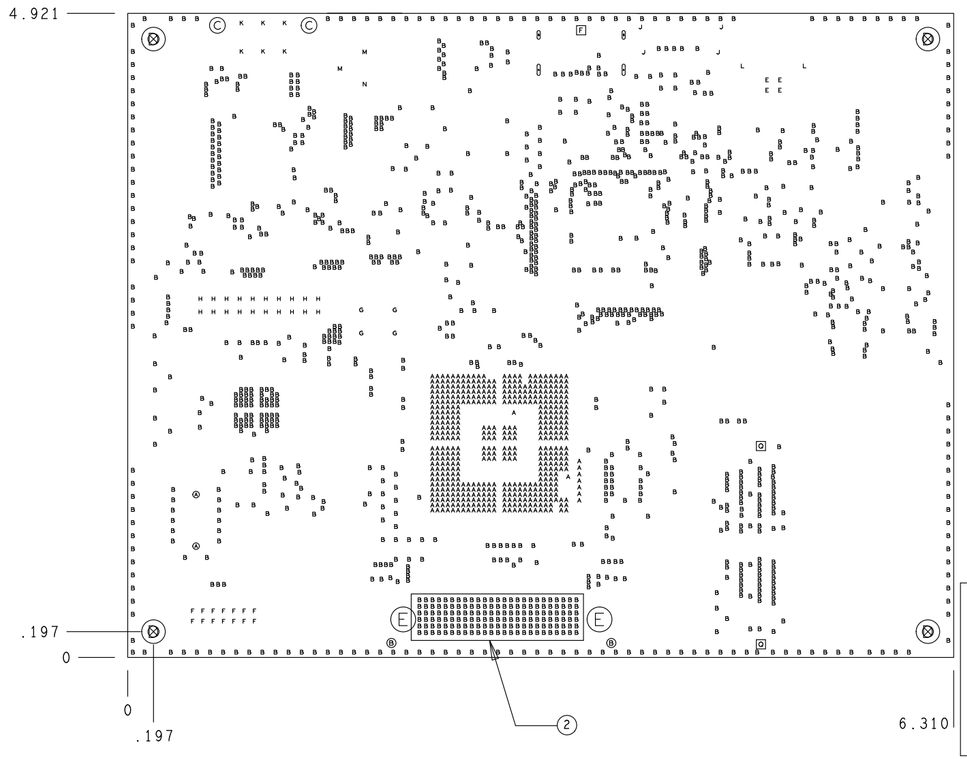
LAYER STACKUP

LAYER 1 - TOP SIDE SIGNAL
LAYER 2 - GND PLANE
LAYER 3 - SIGNAL
LAYER 4 - GND PLANE
LAYER 5 - SIGNAL
LAYER 6 - GND PLANE
LAYER 7 - PWR PLANE
LAYER 8 - PWR PLANE
LAYER 9 - GND PLANE
LAYER 10 - SIGNAL
LAYER 11 - GND PLANE
LAYER 12 - SIGNAL
LAYER 13 - GND PLANE
LAYER 14 - BOTTOM SIDE SIGNAL

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
A	9.0	+3.0/-3.0	PLATED	509
B	12.0	+3.0/-12.0	PLATED	1320
E	36.0	+3.0/-3.0	PLATED	4
F	38.0	+3.0/-3.0	PLATED	14
G	40.0	+3.0/-3.0	PLATED	4
H	42.0	+3.0/-3.0	PLATED	20
J	52.0	+3.0/-3.0	PLATED	4
K	55.0	+3.0/-3.0	PLATED	6
L	90.0	+3.0/-3.0	PLATED	2
M	120.0	+3.0/-3.0	PLATED	2
N	140.0	+3.0/-3.0	PLATED	1
Ⓐ	40.0	+3.0/-3.0	NON-PLATED	2
▣	40.157	+2.992/-2.992	NON-PLATED	2
F	55.118	+1.969/-1.969	NON-PLATED	1
Ⓑ	66.0	+3.0/-3.0	NON-PLATED	2
Ⓒ	118.0	+3.0/-3.0	NON-PLATED	2
Ⓓ	180.0	+3.0/-3.0	NON-PLATED	4
Ⓔ	182.0	+3.0/-3.0	NON-PLATED	2
8	66.929x23.622	+1.969/-1.969	PLATED	2
8	86.614x23.622	+1.969/-1.969	PLATED	2



PRIMARY SIDE VIEW

FAB NOTES:

1. ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE NOTED. ALL BOARD OUTLINE DIMENSION TOLERANCES ARE +/- .010".
2. THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
3. BOARD MATERIAL SHALL BE 180 Tg/340 Td ISOLA FR-370HR OR EQUIVALENT, RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B, RoHS CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT.
4. ALL BOARDS MUST MEET OR EXCEDE ul94-V0 REQUIRMENTS. PCB MUST BEAR THE UL94-0 REGISTERED MATERIAL ID NUMBER.
5. MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .001 INCH.
6. OVERALL BOARD THICKNESS TO BE .079 +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
7. MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
8. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
9. ALL LAYERS TO BE 1/2 OZ STARTING COPPER WEIGHT.
10. FABRICATOR SHALL REMOVE ANY UNUSED PADS ON INTERNAL LAYERS.
11. TRACE WIDTHS WITH NO SPECIFIED IMPEDANCE REQUIREMENTS SHOULD BE BUILT TO INDICATED WIDTH.

PROCESS NOTES:

1. EXCEPT AS NOTED,PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD, FLASH GOLD PROCESS IS ALSO ACCEPTABLE. REQUIRED PLATING THICKNESS: NICKEL 150 MICROINCH MIN, GOLD 5-15 MICROINCHES THK.
2. PLATE INDICATED AREAS (TOP SIDE) WITH ELECTROPLATED GOLD (35-50 MICROINCHES) OVER ELECTROPLATED NICKEL (MINIMUM 100 MICROINCHES).
3. APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC), COLOR: GREEN. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV.
4. FABRICATION VENDOR IS ALLOWED TO ADJUST THE COMPONENT PADS BY A MAXIMUM 1 MIL ON EACH SIDE OVER THE COPPER PAD IN ORDER TO MEET TOOLING REQUIREMENTS WHILE MAINTAINING WEBBING BETWEEN ADJACENT PADS.
5. APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK BOTH SIDES. COLOR: WHITE.

CONTROLLED IMPEDANCE DESIGN

6.8 MIL TRACES ON EXTERNAL LAYERS SHALL BE 50 OHMS SINGLE ENDED

5.7 MIL TRACES ON INTERNAL LAYERS SHALL BE 50 OHMS SINGLE ENDED

5.5 MIL TRACES WITH 5.5 MIL SPACES ON EXTERNAL LAYERS SHALL BE 90 OHMS DIFFERENTIAL

5.4 MIL TRACES WITH 5.6 MIL SPACES ON INTERNAL LAYERS SHALL BE 90 OHMS DIFFERENTIAL

4.75 MIL TRACES WITH 7.25 MIL SPACES ON ALL LAYERS SHALL BE 100 OHMS DIFFERENTIAL

CUSTOMER NAME: TEXAS INSTRUMENTS					
BOARD NAME: HIRES SINGLE DLPC900			DESCRIPTION: DRILL DRAWING		
BOARD NO.: 2513757	REV: H	DATE: 13 OCT 2020	PRJ#:	SH: 21	OF: 21